


# MATERIAL DECLARATION SHEET



Reliable Electronic Solutions

Material	CAT16-J2LF	
Product Line	Chip Array	
Date	31-October-2005	

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
1	Ceramic	Substrate	0.00448	Al <sub>2</sub> O <sub>3</sub>	1344-28-1	96	100	
				SiO <sub>2</sub>	14808-60-7	3		
				Other		1		
2	Conductor	Terminal Electrode	0.00014	Ag-Pd	7440-22-4	92	100	
				Bi <sub>2</sub> O <sub>3</sub>	1304-86-3	5		
				ZrO <sub>2</sub>	1314-23-4	1		
				Other		2		
3	Resistive film	Resistor	0.00003	Glass	65997-18-4	43	100	
				RuO <sub>2</sub>	12036-10-1	36		
				Ag	7440-22-4	7		
				CaO	1305-78-8	6		
				Al <sub>2</sub> O <sub>3</sub>	1344-28-1	1		
				Pd	7440-05-3	1		
				ZnO	1314-13-2	1		
				MnO <sub>2</sub>	1313-13-9	1		
Other		4						
4	Overcoat	Inner	0.00004	Glass	65997-18-4	90	100	
				Al <sub>2</sub> O <sub>3</sub>	1344-28-1	6		
				TiO <sub>2</sub>	13463-67-7	4		

No.	Construction element	Material group	Material weight [g]	Materials	CAS if applicable	Average mass [%]	Sum [%]	Traces
5	Overcoat	Outer	0.00010	Resin		100	100	
6	Side termination	Thick film	0.00003	Ag-Pd	7440-22-4	92	100	
				Bi <sub>2</sub> O <sub>3</sub>	1304-86-3	5		
				ZrO <sub>2</sub>	1314-23-4	1		
				Other		2		
7	Ni plating	Inner	0.00011	Ni	7440-02-0	100	100	
8	Sn plating	Outer	0.00007	Sn	7440-31-5	100	100	
		Total weight	0.00500					